# IGBT - Field Stop II / 4 Lead

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop II Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. In addition, this new device is packaged in a TO–247–4L package that provides significant reduction in  $E_{\rm on}$  Losses compared to standard TO–247–3L package. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

#### **Features**

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Improved Gate Control Lowers Switching Losses
- Separate Emitter Drive Pin
- TO-247-4L for Minimal E<sub>on</sub> Losses
- Optimized for High Speed Switching
- These are Pb-Free Devices

## **Typical Applications**

- Solar Inverter
- Uninterruptible Power Inverter Supplies (UPS)
- Neutral Point Clamp Topology

#### **ABSOLUTE MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-emitter voltage	V <sub>CES</sub>	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	lc	160 40	A
Pulsed collector current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>CM</sub>	160	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	I <sub>F</sub>	160 40	A
Diode pulsed current, T <sub>pulse</sub> limited by T <sub>Jmax</sub>	I <sub>FM</sub>	160	Α
Gate-emitter voltage Transient gate-emitter voltage $(T_{pulse} = 5 \mu s, D < 0.10)$	V <sub>GE</sub>	±20 ±30	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P <sub>D</sub>	536 268	W
Operating junction temperature range	$T_J$	-55 to +175	°C
Storage temperature range	T <sub>stg</sub>	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T <sub>SLD</sub>	260	°C

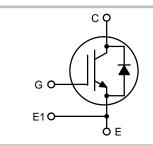
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

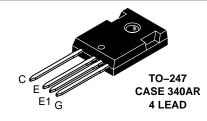


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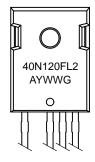
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40 A, 1200 V V<sub>CEsat</sub> = 2.1 V E<sub>on</sub> = 1.7 mJ





#### MARKING DIAGRAM



40N120FL2 = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

#### ORDERING INFORMATION

Device	Package	Shipping
NGTB40N120FL2WAG	TO-247 (Pb-Free)	30 Units / Rail

## THERMAL CHARACTERISTICS

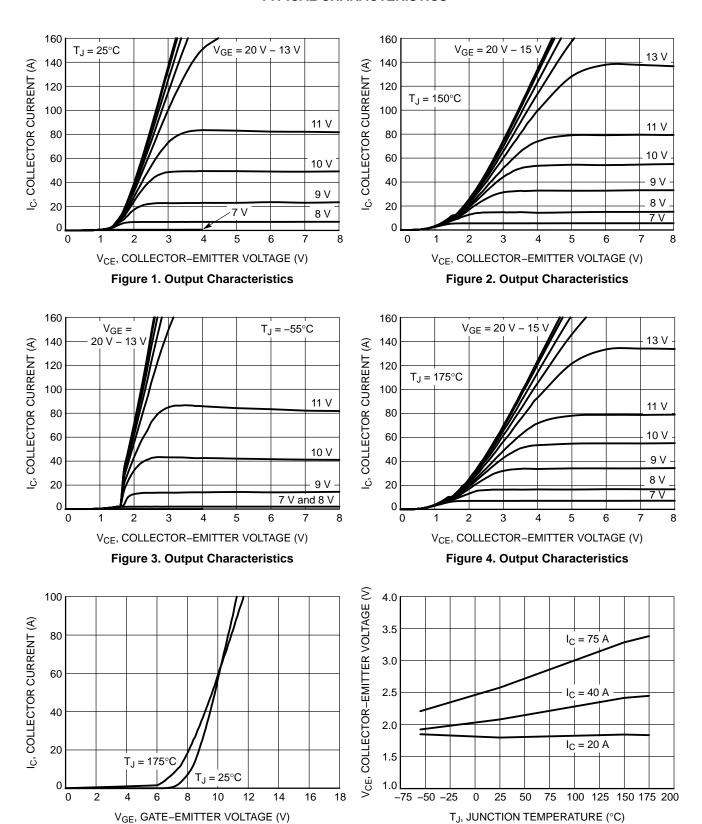
Rating	Symbol	Value	Unit
Thermal resistance junction–to–case, for IGBT	$R_{ heta JC}$	0.28	°C/W
Thermal resistance junction-to-case, for Diode		0.50	°C/W
Thermal resistance junction-to-ambient		40	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>.1</sub> = 25°C unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•					
Collector–emitter breakdown voltage, gate–emitter short–circuited	$V_{GE} = 0 \text{ V, } I_{C} = 500  \mu\text{A}$	V <sub>(BR)CES</sub>	1200	_	-	V
Collector–emitter saturation voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>CEsat</sub>	_ _	2.1 2.4	2.4 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 400 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	$V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}$ $V_{GE} = 0 \text{ V}, V_{CE} = 1200 \text{ V}, T_{J} = 175^{\circ}\text{C}$	I <sub>CES</sub>	- -	- 4.0	0.4 -	mA
Gate leakage current, collector–emitter short–circuited	V <sub>GE</sub> = 20 V , V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	200	nA
Input capacitance	1	C <sub>ies</sub>	_	7500	-	pF
Output capacitance	V <sub>CE</sub> = 20 V, V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	_	136	_	
Reverse transfer capacitance	1	C <sub>res</sub>	_	230	_	
Gate charge total		$Q_{g}$	-	313	-	nC
Gate to emitter charge	$V_{CE} = 600 \text{ V}, I_{C} = 40 \text{ A}, V_{GE} = 15 \text{ V}$	Q <sub>ge</sub>	-	61	-	
Gate to collector charge	1	Q <sub>gc</sub>	-	151	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD				•	
Turn-on delay time		t <sub>d(on)</sub>	_	30	_	ns
Rise time	1	t <sub>r</sub>	-	33	-	
Turn-off delay time	T <sub>J</sub> = 25°C	t <sub>d(off)</sub>	-	145	-	
Fall time	$V_{CC} = 600 \text{ V, } I_{C} = 40 \text{ A}$ $R_g = 10 \Omega$ $V_{GE} = 15 \text{ V}$	t <sub>f</sub>	-	95	-	
Turn-on switching loss		E <sub>on</sub>	_	1.7	_	mJ
Turn-off switching loss	1	E <sub>off</sub>	_	1.1	_	
Total switching loss	1	E <sub>ts</sub>	_	2.8	_	
Turn-on delay time		t <sub>d(on)</sub>	-	28	-	ns
Rise time	1	t <sub>r</sub>	-	37	-	
Turn-off delay time	T <sub>J</sub> = 175°C	t <sub>d(off)</sub>	-	165	-	
Fall time	$V_{CC} = 600 \text{ V, } I_{C} = 40 \text{ A}$ $R_{a} = 10 \Omega$	t <sub>f</sub>	-	195	-	
Turn-on switching loss	$R_g = 10 \Omega$ $V_{GE} = 15 V$	E <sub>on</sub>	-	2.5	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	2.5	-	
Total switching loss		E <sub>ts</sub>	-	5.0	-	
DIODE CHARACTERISTIC						
Forward voltage	$V_{GE} = 0 \text{ V, } I_F = 40 \text{ A}$ $V_{GE} = 0 \text{ V, } I_F = 40 \text{ A, } T_J = 175^{\circ}\text{C}$	V <sub>F</sub>		2.00 2.30	2.40 -	V
Reverse recovery time	$T_J = 25^{\circ}C$ $I_F = 40 \text{ A, V}_R = 400 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	t <sub>rr</sub>	-	240	_	ns
Reverse recovery charge		Q <sub>rr</sub>	-	2.5	_	μC
Reverse recovery current		I <sub>rrm</sub>	-	18	_	Α
Reverse recovery time	T <sub>J</sub> = 175°C	t <sub>rr</sub>	-	392	-	ns
Reverse recovery charge	I <sub>F</sub> = 40 A, V <sub>R</sub> = 400 V di <sub>F</sub> /dt = 200 A/μs	Q <sub>rr</sub>	-	5.4	-	μс
Reverse recovery current		I <sub>rrm</sub>	_	26	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**



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Figure 6. V<sub>CE(sat)</sub> vs. T<sub>J</sub>

Figure 5. Typical Transfer Characteristics

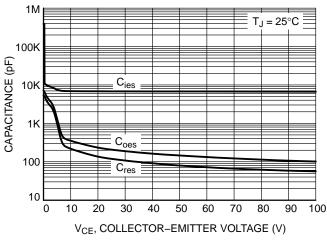


Figure 7. Typical Capacitance

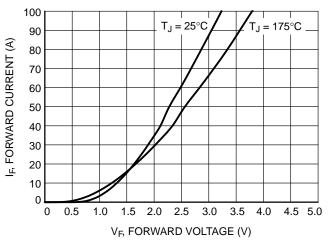


Figure 8. Diode Forward Characteristics

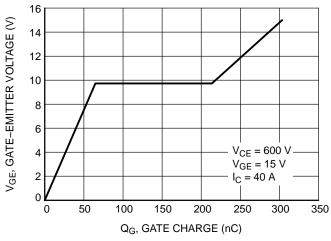


Figure 9. Typical Gate Charge

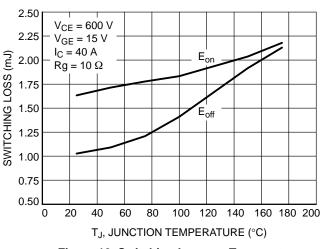


Figure 10. Switching Loss vs. Temperature

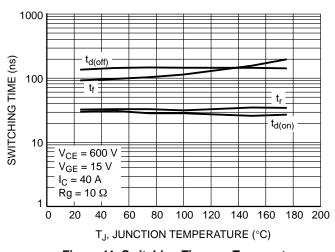


Figure 11. Switching Time vs. Temperature

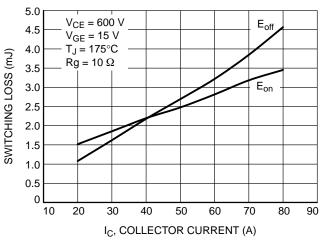


Figure 12. Switching Loss vs. IC

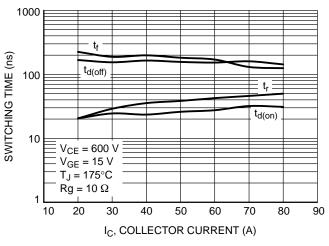


Figure 13. Switching Time vs. IC

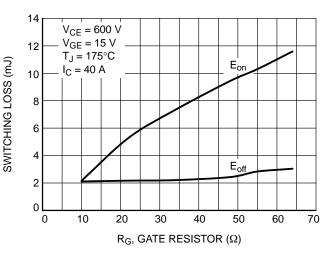


Figure 14. Switching Loss vs. R<sub>G</sub>

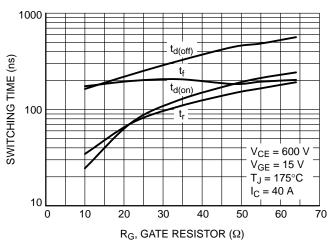


Figure 15. Switching Time vs. R<sub>G</sub>

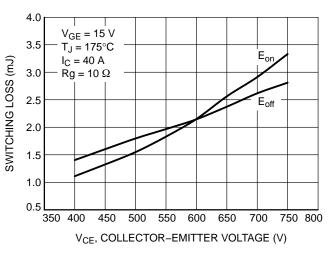


Figure 16. Switching Loss vs. V<sub>CE</sub>

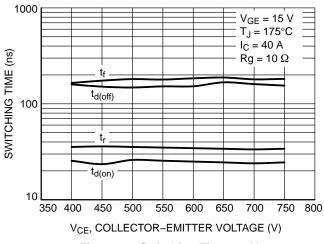


Figure 17. Switching Time vs. V<sub>CE</sub>

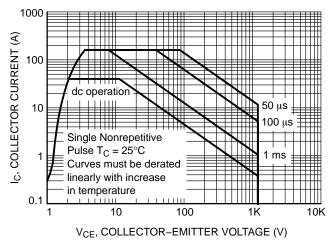


Figure 18. Safe Operating Area

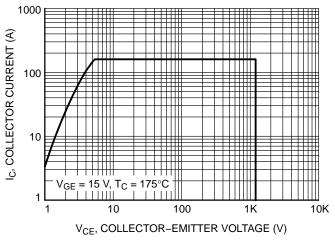


Figure 19. Reverse Bias Safe Operating Area

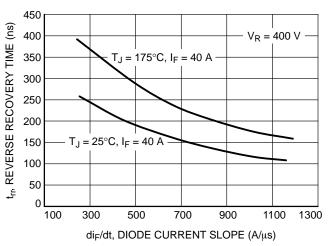


Figure 20. t<sub>rr</sub> vs. di<sub>F</sub>/dt

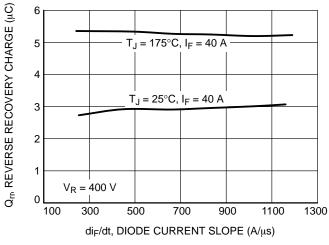


Figure 21. Q<sub>rr</sub> vs. di<sub>F</sub>/dt

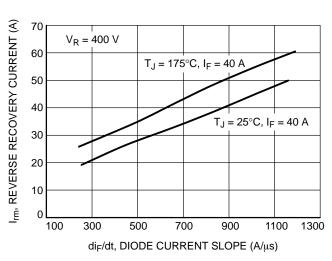


Figure 22. I<sub>rm</sub> vs. di<sub>F</sub>/dt

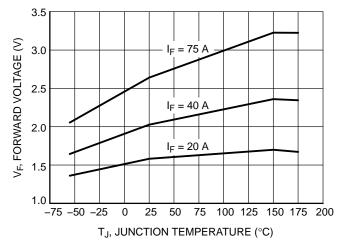


Figure 23. V<sub>F</sub> vs. T<sub>J</sub>

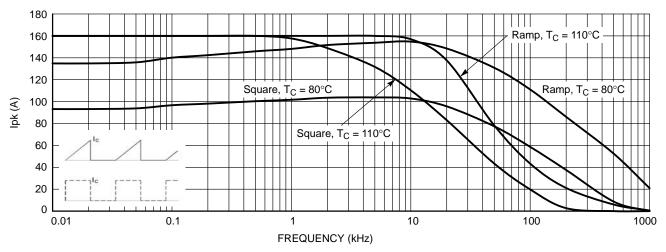


Figure 24. Collector Current vs. Switching Frequency

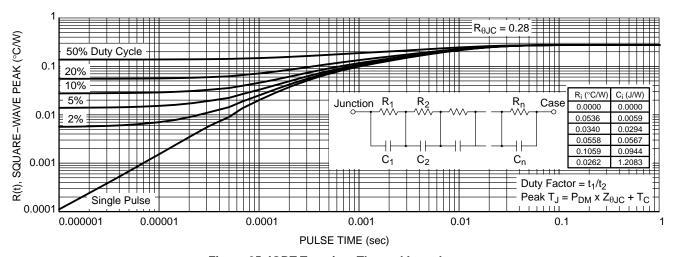


Figure 25. IGBT Transient Thermal Impedance

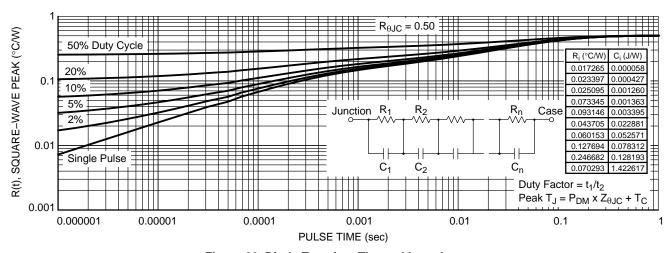


Figure 26. Diode Transient Thermal Impedance

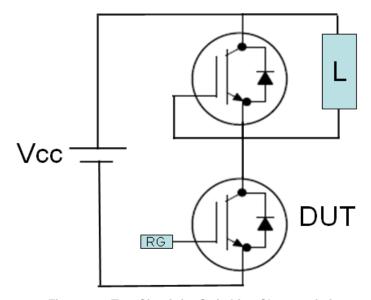


Figure 27. Test Circuit for Switching Characteristics

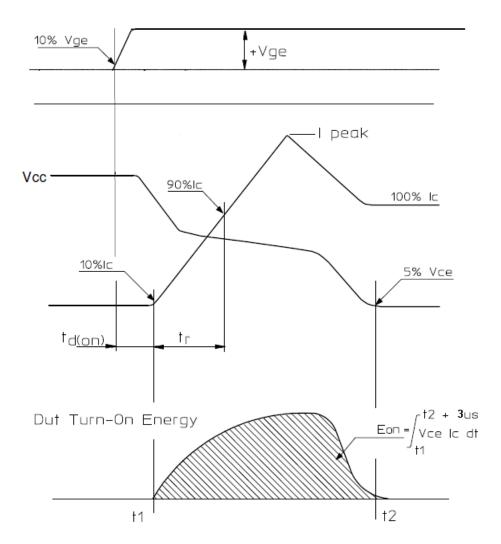


Figure 28. Definition of Turn On Waveform

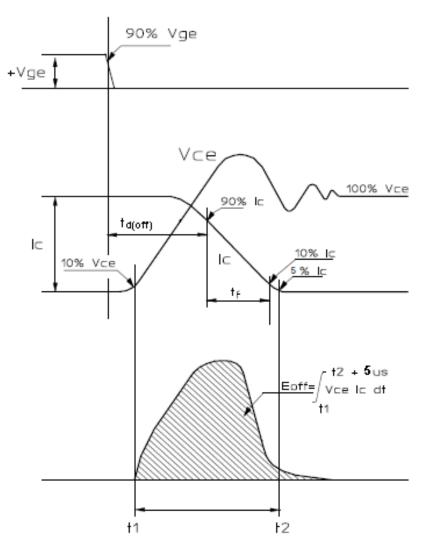
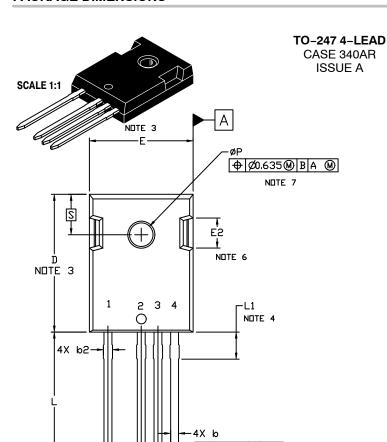
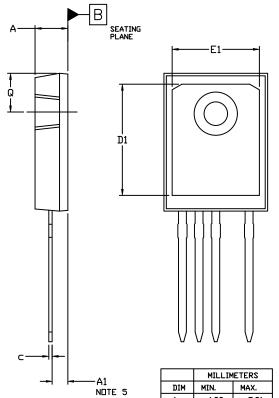


Figure 29. Definition of Turn Off Waveform



**DATE 07 MAY 2020** 



#### NOTES:

2X e

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

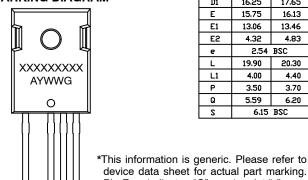
◆ 0.25 M B A M

CONTROLLING DIMENSION: MILLIMETER

e

- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE DUTERMOST EXTREME OF THE PLASTIC BODY.
- 4. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.
- DIMENSION AT TO BE MEASURED IN THE REGION DEFINED BY L1.
- NOTCHES ARE REQUIRED BUT THEIR SHAPE IS OPTIONAL.
- 7. DIAMETER P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 3.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 4.20.

## **GENERIC MARKING DIAGRAM\***



Α	4.83	5.21	
A1	2.29	2.54	
b	1.10	1.30	
b2	1.30	1.50	
C	0.50	0.70	
D	20.80	21.10	
D1	16.25	17.65	
Ε	15.75	16.13	
E1	13.06	13.46	
E2	4.32	4.83	
e	2.54 BSC		
L	19.90	20.30	
L1	4.00	4.40	
Р	3.50	3.70	
Q	5.59	6.20	
S	6.15 BSC		

XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

or may not be present. Some products may not follow the Generic Marking.

device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "■", may

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 VS-CPV364M4KPBF
 NGTB25N120FL2WAG
 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

 APT40GR120B2SCD10
 APT15GT120BRG
 APT20GT60BRG
 NGTB75N65FL2WAG
 NGTG15N120FL2WG
 IXA30RG1200DHGLB

 IXA40RG1200DHGLB
 APT70GR65B2DU40
 NTE3320
 IHFW40N65R5SXKSA1
 APT70GR120J
 APT35GP120JDQ2

 IKZA40N65RH5XKSA1
 IKFW75N65ES5XKSA1
 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
 IKFW40N65ES5XKSA1

 IKFW60N65ES5XKSA1
 IMBG120R090M1HXTMA1
 IMBG120R220M1HXTMA1
 XD15H120CX1
 XD25H120CX0
 XP15PJS120CL1B1

 IGW30N60H3FKSA1
 STGWA8M120DF3
 IGW08T120FKSA1
 IGW75N60H3FKSA1
 HGTG40N60B3
 FGH60N60SMD\_F085

 FGH75T65UPD
 STGWA15H120F2
 IKA10N60TXKSA1
 IHW20N120R5XKSA1
 RJH60D2DPP-M0#T2
 IKP20N60TXKSA1

 IHW20N65R5XKSA1
 IDW40E65D2FKSA1